

November 14th, 2019

PCN20191114

Process Change Notification (PCN)**Change Detail:**

Be advised, Silicon Power Corporation has added a 25µm (~0.001") silicon wafer back-grinding process step to the wafer production process of the SP205 product family.

Part Number	Introduction of Change	Semiconductor Lot
SP205-01	Date Code 1944	219-506174.000
SP205-01T	Date Code 1944	219-506174.000

Purpose(s) of Change:

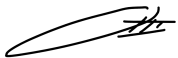
1. To improve uniformity of the pre-metalized back-side surface of the silicon wafer
2. To improve sputtered solderable metal adhesion to the silicon wafer
3. Yields a more consistent ohmic contact of back-side metal to the silicon wafer
4. To Improve overall product yield

Impact on Performance: Minimizes capacitor discharge test variability

Data Sheet Changes: None

Process change evaluated and samples tested with positive results by: Defense Micro Electronics Activity, McClellan, CA 95652-2100

Respectfully,



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